



# MM 980nm 14Gbps PD (Top Illumination)

QZP14MM0980T101 QZP14MM0980T102 QZP14MM0980T103



01 Descriptions Features Application

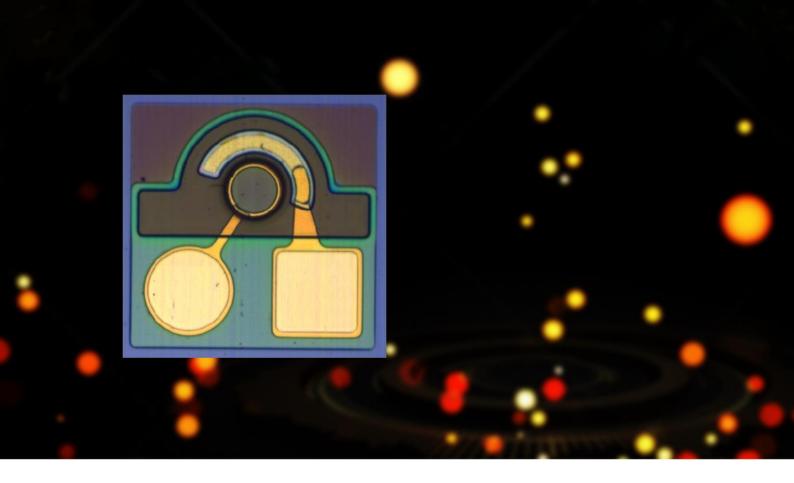
02 Absolute Maximum Ratings Electro-Optic Characteristics



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### **Description**

The QuantumZ - **QZP14MM0980TX0X** is a front-side illuminated InGaAs PIN photodiode chip has 64um detection window and excellent performances, like low capacitance, high responsivity, low dark current, and reliability in field. The device is available in singlet (1x1) or array configurations (1x4) and are compatible with wire-bonding and flip-chip bonding.

#### **Features**

- High responsivity & data rates from DC to 14Gbps
- Low dark current, operating voltage & capacitance
- Topside anode & cathode configuration
- Available as single chip & 4 channel array
- Available application for COB & flip chip processes
- High humidity robustness compliant with GR-468
- Halogen & RoHS compliant

#### **Applications**

- Smart cables & consumer applications
- · Single channel & parallel fiber optical communication links



## **Absolute Maximum Ratings**

Parameter	Rating	Unit
Operating temperature	0 to 100	°C
Storage temperature	-40 to 125	°C
Mounting temperature (max. 10sec)	260	°C

## **Electro-Optic Characteristics**

Parameter	Symbol	Conditions	Ratings			Unit
			Min.	Тур.	Max.	Onit
Aperture diameter	d			60		μm
Wavelength	λ		800	980	1100	nm
Responsivity	R		0.55	0.6		A/W
Dark current	l <sub>d</sub>	U <sub>op</sub> =-2V			150	pА
Breakdown voltage	U <sub>BD</sub>	I=-10uA		-40		V
Capacitance	С	U <sub>op</sub> =-2V		150		fF
3dB-bandwidth	f <sub>3dB</sub>	U <sub>op</sub> =-2V	10	12		GHz



## **Chip Outer Dimensions**

Parameter	Min.	Тур.	Max.
Die length	225	250	275
Die width	225	250	275
Die height	125	150	175

#### **RoHS Compliance**

QuantumZ insists, via continuous improvement in technology and experiences, to utilize non-hazardous materials for manufacturing green products that are in compliance with the regulation as well as customers' GP demands. The relevant evidence of RoHS compliance is held as part of our controlled documentation for each of our compliant products.



## **Ordering Information**

Product code	Data Rate	Description	Shipment Package
QZP14MM0980T101	14Gbps	Single PD chip	Diced wafer on metal lead frame (1)
QZP14MM0980T401	14Gbps	1x4 PD array	Diced wafer on metal lead frame (1)
QZP14MM0980T102	14Gbps	Single PD chip	Grip ring (2)
QZP14MM0980T402	14Gbps	1x4 PD array	Grip ring (2)
QZP14MM0980T103	14Gbps	Single PD chip	Gel-Pak (3)
QZP14MM0980T403	14Gbps	1x4 PD array	Gel-Pak (3)

(1) Full diced 4" wafer on UV tape on metal lead frame Ø 230mm, electronic wafer map provided (standard high volume)

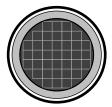
(2) Known Good Dies on UV tape on grip ring Ø 150mm (medium volume)

(3) Known Good Dies in 2" Gel-Pak (low volume)

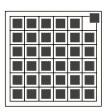


Diced wafer on UV tape on metal lead

Quantum 🕿



Grip ring



Gel-Pak

